CHIP COIL (CHIP INDUCTORS) LQW2BHN□□□□03L REFERENCE SPECIFICATION

1. Scope

This reference specification applies to LQW2BHN_03L series, Chip coil (Chip Inductors).

2. Part Numbering

(ex)	LQ	W	2B	H	N	3N3	D	0	3	L
	Product ID	Structure	Dimension (L×W)	Applications and Characteristics	Category	Inductance	Tolerance	Features	Electrode	Packaging L:Taping ∗B:Bulk

∗Bulk packing also available. (A product is put in the plastic bag under the taping conditions.)

3. Rating

・Operating Temperature Range -40°C to +85°C
・Storage Temperature Range. -40°C to +85°C

Customer Part Number	MURATA Part Number	Inductance (nH)	Inductance Tolerance	Q (min.)	DC Resistance (Ωmax.)	Self Resonant Frequency (MHz min.)	Rated Current (mA)
	LQW2BHN3N3D03L	3.3	D:±0.5nH	10	0.05	6000	910
	LQW2BHN6N8D03L	6.8		20	0.11	5400	680
	LQW2BHN8N2D03L	8.2			0.12	3900	630
	LQW2BHN10NJ03L	10	J:± 5 %	30	0.03	3300	1320
	LQW2BHN12NJ03L	12			0.11	3200	680
	LQW2BHN15NJ03L	15			0.12	2700	630
	LQW2BHN18NJ03L	18			0.10	2600	690
	LQW2BHN22NJ03L	22			0.09	2100	720
	LQW2BHN27NJ03L	27		40	0.17	2300	540
	LQW2BHN33NG03L	33	G:± 2% J:± 5%		0.15	1900	570
	LQW2BHN33NJ03L						
	LQW2BHN39NG03L	39			0.09	1700	730
	LQW2BHN39NJ03L						
	LQW2BHN47NG03L	47			0.23	1600	450
	LQW2BHN47NJ03L						
	LQW2BHN56NG03L	56			0.26	1500	430
	LQW2BHN56NJ03L						
	LQW2BHN68NG03L	68			0.23	1200	460
	LQW2BHN68NJ03L						
	LQW2BHN82NG03L	82			0.42	1100	320
	LQW2BHN82NJ03L						
	LQW2BHNR10G03L	100		35	0.55	900	270
	LQW2BHNR10J03L			40	0.38		350
	LQW2BHNR12G03L	120			0.40	750	320
	LQW2BHNR12J03L						
	LQW2BHNR15G03L	150		30	0.68	350	260
	LQW2BHNR15J03L				0.47		390
	LQW2BHNR18G03L	180		35	0.71	700	250
	LQW2BHNR18J03L						
	LQW2BHNR22G03L	220			0.70	500	240
	LQW2BHNR22J03L						
	LQW2BHNR27J03L	270	J:± 5% K:±10%	15	2.0	550	190
	LQW2BHNR27K03L						
	LQW2BHNR33J03L	330			2.2	500	180
	LQW2BHNR33K03L						
	LQW2BHNR39J03L	390			2.5	400	170
	LQW2BHNR39K03L						
	LQW2BHNR47J03L	470			2.8	350	160
	LQW2BHNR47K03L						

4. Testing Conditions

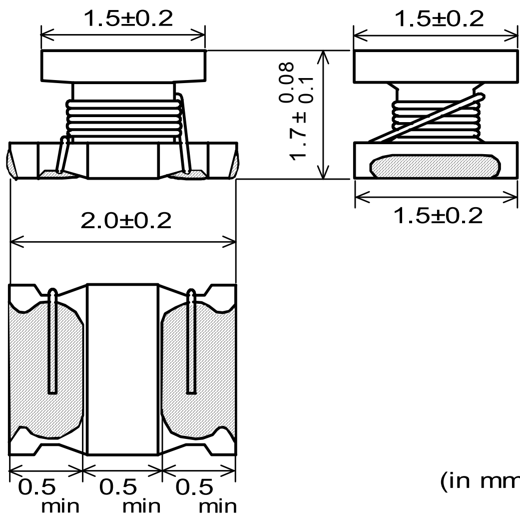
《Unless otherwise specified》

Temperature : Ordinary Temperature / 15°C to 35°C
Humidity : Ordinary Humidity / 25%(RH) to 85%(RH)

《In case of doubt》

Temperature : 20°C±2°C
Humidity : 60%(RH) to 70%(RH)
Atmospheric Pressure : 86kPa to 106 kPa

5. Appearance and Dimensions



(in mm)

■Unit Mass(Typical value)
0.009g

6. Electrical Performance

No.	Item	Specification	Test Method
6.1	Inductance	Inductance shall meet item 3.	Measuring Equipment：KEYSIGHT E4991A or equivalent Measuring Frequency：100MHz / 3.3 nH to 220 nH 10MHz / 270 nH to 470 nH Measuring Method：See the endnote . <Electrical Performance:Measuring Method of Inductance/Q>
6.2	Q	Q shall meet item 3.	Measuring Equipment：KEYSIGHT E4991A or equivalent Measuring Frequency：250MHz / 3.3nH to 39nH 200MHz / 47nH to 68nH 150MHz / 82nH to 150nH 100MHz / 180nH to 220nH 25.2MHz / 270nH to 470nH
6.3	DC Resistance	DC Resistance shall meet item 3.	Measuring Equipment：Digital multi meter
6.4	Self Resonant Frequency(S.R.F)	S.R.F shall meet item 3.	Measuring Equipment：KEYSIGHT E4991A or equivalent
6.5	Rated Current	Self temperature rise shall be limited to 20 °C max. Inductance Change：within ± 10%	The rated current is applied.

7. Mechanical Performance

No.	Item	Specification	Test Method
7.1	Shear Test	Chip coil shall not be damaged after tested as test method.	Substrate：Glass-epoxy substrate Applied Direction： Force：10N Hold Duration：5s±1s
7.2	Bending Test		Substrate：Glass-epoxy substrate (100mm×40mm×1.6mm) Speed of Applying Force：1mm / s Deflection：2mm Hold Duration：30 s
7.3	Vibration		Oscillation Frequency：10Hz ~ 55Hz ~ 10Hz for 1 min Total Amplitude：1.5mm Testing Time：A period of 2 hours in each of 3 mutually perpendicular directions. (Total 6h)
7.4	Solderability	The wetting area of the electrode shall be at least 90% covered with new solder coating.	Flux：Ethanol solution of rosin 25(wt)% (Immersed for 5s to 10s) Solder：Sn-3.0Ag-0.5Cu Pre-Heating：150°C±10°C / 60s to 90s Solder Temperature：240°C±5°C Immersion Time：3s±1s
7.5	Resistance to Soldering Heat	Appearance：No damage Inductance Change：within ± 5%	Flux：Ethanol solution of rosin 25(wt)% (Immersed for 5s to 10s) Solder：Sn-3.0Ag-0.5Cu Pre-Heating：150°C±10°C / 60s to 90s Solder Temperature：270°C±5°C Immersion Time：10s±1s Then measured after exposure in the room condition for 24h±2h.

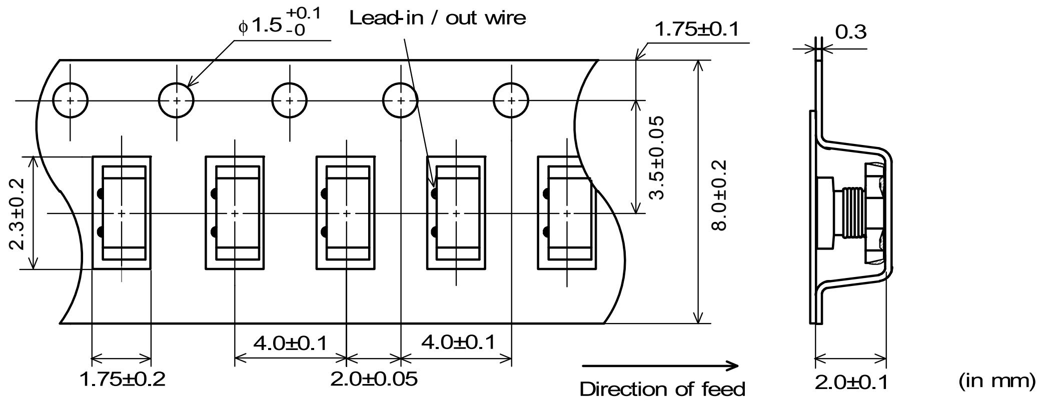
8. Environmental Performance

It shall be soldered on the substrate.

No.	Item	Specification	Test Method
8.1	Heat Resistance	Appearance：No damage Inductance Change：within ±5% Q Change：within ±20%	Temperature：85°C±2°C Time：1000h (+48h , -0h) Then measured after exposure in the room condition for 24h±2h.
8.2	Cold Resistance		Temperature：-40°C±2°C Time：1000h (+48h ,-0h) Then measured after exposure in the room condition for 24h±2h.
8.3	Humidity		Temperature：40°C±2°C Humidity：90%(RH) to 95%(RH) Time：1000h (+48h , -0h) Then measured after exposure in the room condition for 24h±2h.
8.4	Temperature Cycle		1 cycle： 1 step：-40°C±2°C / 30 min ± 3 min 2 step：Ordinary temp. / 10 min to 15 min 3 step：+85°C±2°C / 30 min ± 3 min 4 step：Ordinary temp. / 10 min to 15 min Total of 10 cycles Then measured after exposure in the room condition for 24h±2h.

9. Specification of Packaging

9.1 Appearance and Dimensions of plastic tape (8mm-wide)



・Dimension of the Cavity is measured at the bottom side.

9.2 Specification of Taping

(1) Packing quantity (standard quantity)
2,000 pcs / reel

(2) Packing Method
Products shall be packed in the each embossed cavity of plastic tape and sealed by cover tape.

(3) Sprocket hole
Sprocket holes are to the right as the tape is pulled toward the user.

(4) Spliced point
Plastic tape and Cover tape has no spliced point.

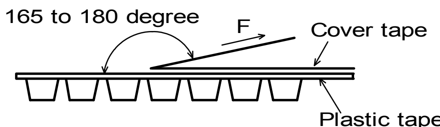
(5) Missing components number
Missing components number within 0.1 % of the number per reel or 1 pc., whichever is greater, and are not continuous. The specified quantity per reel is kept.

9.3 Pull Strength

Plastic tape	10N min.
Cover tape	

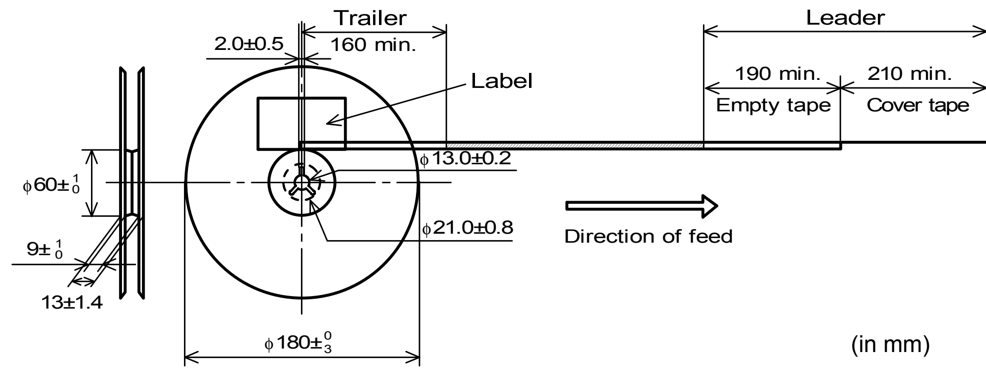
9.4 Peeling off force of cover tape

Speed of Peeling off	300mm / min
Peeling off force	0.1N to 0.7N (minimum value is typical)



9.5 Dimensions of Leader-tape,Trailer and Reel

There shall be leader-tape (top tape and empty tape) and trailer-tape (empty tape) as follows.



(in mm)

9.6 Marking for reel

Customer part number, MURATA part number, Inspection number(∗1), RoHS marking(∗2), Quantity etc ･･･

∗1) <Expression of Inspection No.> □□ OOOO ××× (1) (2) (3)

(1) Factory Code

(2) Date First digit : Year / Last digit of year
Second digit : Month / Jan. to Sep. → 1 to 9, Oct. to Dec. → O, N, D
Third, Fourth digit : Day

(3) Serial No.

∗2) « Expression of RoHS marking » ROHS – Y (△) (1) (2)

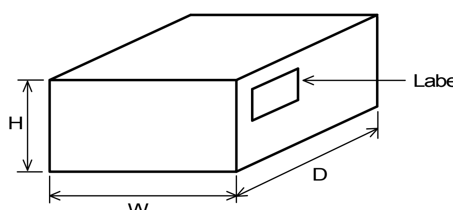
(1) RoHS regulation conformity

(2) MURATA classification number

9.7 Marking for Outside package (corrugated paper box)

Customer name, Purchasing order number, Customer part number, MURATA part number, RoHS Marking (∗2) , Quantity, etc ･･･

9.8. Specification of Outer Case



Outer Case Dimensions (mm)			Standard Reel Quantity in Outer Case (Reel)
W	D	H	
186	186	93	5

∗ Above Outer Case size is typical. It depends on a quantity of an order.

10. ⚠ Caution

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects which might directly cause damage to the third party's life, body or property.

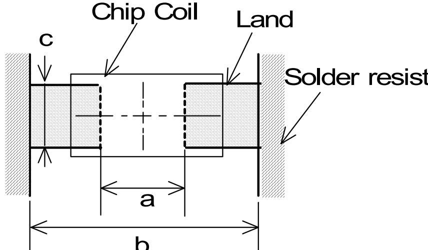
(1) Aircraft equipment
(2) Aerospace equipment
(3) Undersea equipment
(4) Power plant control equipment
(5) Medical equipment
(6) Transportation equipment (vehicles, trains, ships, etc.)
(7) Traffic signal equipment
(8) Disaster prevention / crime prevention equipment
(9) Data-processing equipment
(10) Applications of similar complexity and /or reliability requirements to the applications listed in the above

11. Notice

This product is designed for solder mounting.
Please consult us in advance for applying other mounting method such as conductive adhesive.

11.1 Land pattern designing

Recommended land patterns for flow and reflow soldering are as follows:
These have been designed for Electric characteristics and solderability.
Please follow the recommended patterns. Otherwise, their performance which includes electrical performance or solderability may be affected, or result to "position shift" in soldering process.



a	0.8
b	3.0
c	1.2

(in mm)

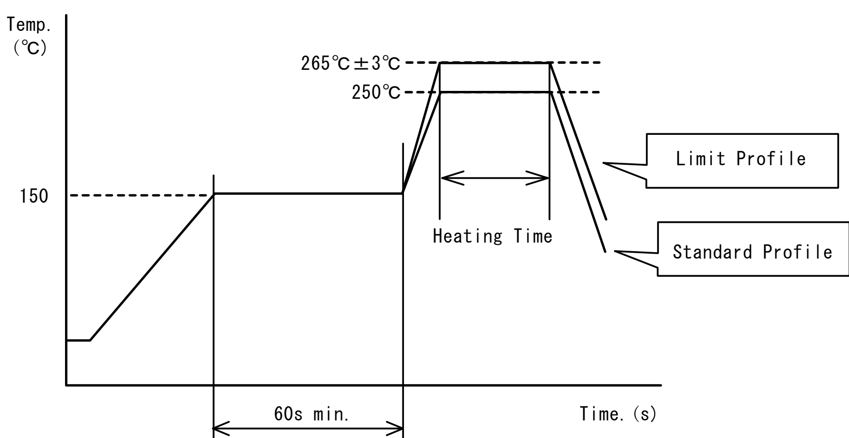
11.2 Flux, Solder

- Use rosin-based flux.
  Don’t use highly acidic flux with halide content exceeding 0.2(wt)% (chlorine conversion value).
  Don’t use water-soluble flux.
- Use Sn-3.0Ag-0.5Cu solder.
- Standard thickness of solder paste : 200 μm to 300 μm.

11.3 Flow soldering / Reflow soldering conditions

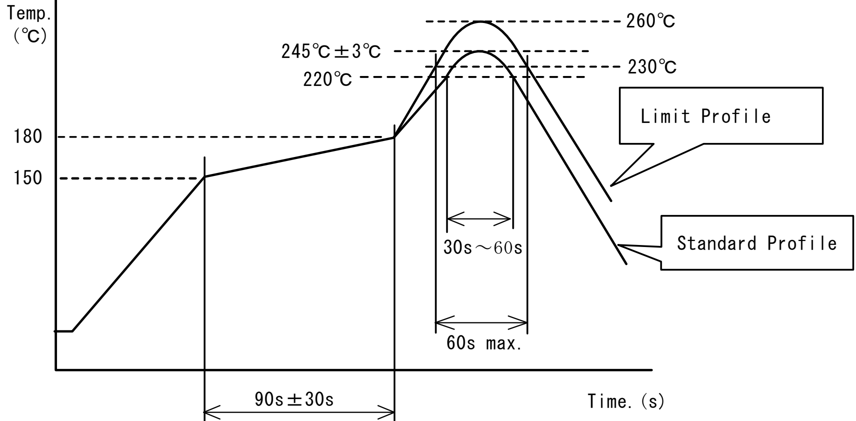
- Pre-heating should be in such a way that the temperature difference between solder and product surface is limited to 150°C max. Cooling into solvent after soldering also should be in such a way that the temperature difference is limited to 100°C max.
  Insufficient pre-heating may cause cracks on the product, resulting in the deterioration of products quality.
- Standard soldering profile and the limit soldering profile is as follows.
  The excessive limit soldering conditions may cause leaching of the electrode and / or resulting in the deterioration of product quality.
- Soldering profile

(1)Flow soldering profile



	Standard Profile	Limit Profile
Pre-heating	150℃、60s min.	
Heating	250℃､4s～6s	265℃±3℃､5s
Cycle of flow	2 times	2 times

(2)Reflow soldering profile



	Standard Profile	Limit Profile
Pre-heating	150°C～180°C 、90s±30s	
Heating	above 220°C､30s～60s	above 230°C､60s max.
Peak temperature	245°C±3°C	260°C,10s
Cycle of reflow	2 times	2 times

11.4 Reworking with soldering iron

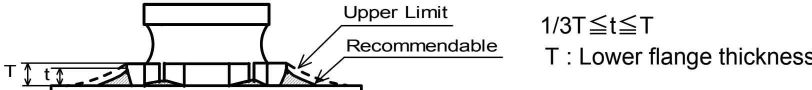
The following conditions must be strictly followed when using a soldering iron.

Pre-heating	150°C,1 min
Tip temperature	350°C max.
Soldering iron output	80W max.
Tip diameter	ϕ3mm max.
Soldering time	3(+1,-0)s
Time	2 times

Note : Do not directly touch the products with the tip of the soldering iron in order to prevent the crack on the products due to the thermal shock.

11.5 Solder Volume

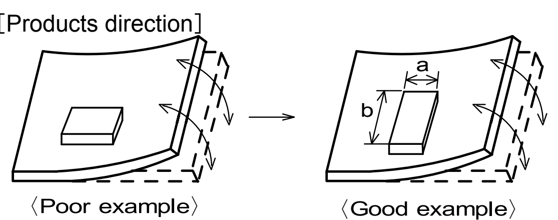
・Solder shall be used not to be exceed the upper limits as shown below.
・Accordingly increasing the solder volume, the mechanical stress to Chip is also increased.
Exceeding solder volume may cause the failure of mechanical or electrical performance.



1/3T≦t≦T
T : Lower flange thickness

11.6 Product's location

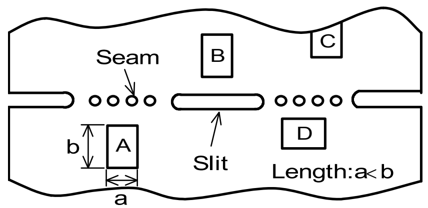
The following shall be considered when designing and laying out P.C.B.'s.
(1) P.C.B. shall be designed so that products are not subject to the mechanical stress due to warping the board.



Products shall be located in the sideways direction (Length:a＜b) to the mechanical stress.

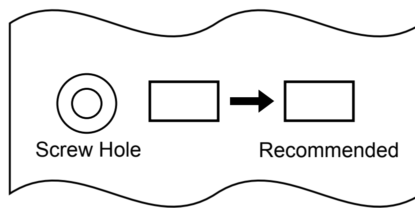
(2) Components location on P.C.B. separation.
It is effective to implement the following measures, to reduce stress in separating the board.
It is best to implement all of the following three measures; however, implement as many measures as possible to reduce stress.

Contents of Measures	Stress Level
(1) Turn the mounting direction of the component parallel to the board separation surface.	A > D *1
(2) Add slits in the board separation part.	A > B
(3) Keep the mounting position of the component away from the board separation surface.	A > C



*1 A > D is valid when stress is added vertically to the perforation as with Hand Separation.
If a Cutting Disc is used, stress will be diagonal to the PCB, therefore A > D is invalid.

(3) Mounting Components Near Screw Holes
When a component is mounted near a screw hole, it may be affected by the board deflection that occurs during the tightening of the screw. Mount the component in a position as far away from the screw holes as possible.



11.7 Cleaning Conditions

Products shall be cleaned on the following conditions.

(1) Cleaning temperature shall be limited to 60°C max. (40°C max for IPA.)

(2) Ultrasonic cleaning shall comply with the following conditions with avoiding the resonance phenomenon at the mounted products and P.C.B.

Power : 20 W / l max.   Frequency : 28kHz to 40kHz   Time : 5 min max.

(3) Cleaner

1. Alcohol type cleaner
   Isopropyl alcohol (IPA)
2. Aqueous agent
   PINE ALPHA ST-100S

(4) There shall be no residual flux and residual cleaner after cleaning.
In the case of using aqueous agent, products shall be dried completely after rinse with de-ionized water in order to remove the cleaner.

(5) Other cleaning   Please contact us.

11.8 Resin coating

The inductance value may change due to high cure-stress of resin to be used for coating/molding products.
An open circuit issue may occur by mechanical stress caused by the resin, amount/cured shape of resin, or operating condition etc. Some resin contains some impurities or chloride possible to generate chlorine by hydrolysis under some operating condition may cause corrosion of wire of coil, leading to open circuit.
So, please pay your careful attention when you select resin in case of coating/molding the products with the resin.
Prior to use the coating resin, please make sure no reliability issue is observed by evaluating products mounted on your board.

11.9 Caution for use

- Sharp material such as a pair of tweezers or other material such as bristles of cleaning brush, shall not be touched to the winding portion to prevent the breaking of wire.
- Mechanical shock should not be applied to the products mounted on the board to prevent the breaking of the core.

11.10 Handling of a substrate

After mounting products on a substrate, do not apply any stress to the product caused by bending or twisting to the substrate when cropping the substrate, inserting and removing a connector from the substrate or tightening screw to the substrate.
Excessive mechanical stress may cause cracking in the product.

Bending   Twisting

11.12 Storage and Handing Requirements

(1) Storage period

Use the products within 12 months after delivered.
Solderability should be checked if this period is exceeded.

(2) Storage conditions

- Products should be stored in the warehouse on the following conditions.

  Temperature : -10°C to 40°C
  Humidity : 15% to 85% relative humidity No rapid change on temperature and humidity

  The electrode of the products is coated with solder. Don't keep products in corrosive gases such as sulfur, chlorine gas or acid, or it may cause oxidization of electrode, resulting in poor solderability.
- Products should not be stored on bulk packaging condition to prevent the chipping of the core and the breaking of winding wire caused by the collision between the products.
- Products should be stored on the palette for the prevention of the influence from humidity, dust and so on.
- Products should be stored in the warehouse without heat shock, vibration, direct sunlight and so on.

(3) Handling Condition

Care should be taken when transporting or handling product to avoid excessive vibration or mechanical shock.

12. ⚠ Note

(1)Please make sure that your product has been evaluated in view of your specifications with our product being mounted to your product.
(2)You are requested not to use our product deviating from the reference specifications.
(3)The contents of this reference specification are subject to change without advance notice.
Please approve our product specifications or transact the approval sheet for product specifications before ordering.

< Electrical Performance:Measuring Method of Inductance / Q >

(1) Residual elements and stray elements of test fixture can be described by F-parameter shown in following.

Test Head — Test fixture — Product
(Zm, I_1, V_1, $\begin{pmatrix} A & B \\ C & D \end{pmatrix}$, I_2, V_2, Zx)

$$\begin{bmatrix} V_1 \\ I_1 \end{bmatrix} = \begin{bmatrix} A & B \\ C & D \end{bmatrix} \begin{bmatrix} V_2 \\ I_2 \end{bmatrix}$$

(2) The impedance of chip coil Zx and measured value Zm can be described by input/output current/voltage.

$$Zm = \frac{V_1}{I_1}, \quad Zx = \frac{V_2}{I_2}$$

(3) Thus,the relation between Zx and Zm is following;

$$Zx = \alpha \frac{Zm - \beta}{1 - Zm\Gamma}$$

where, $\alpha = D / A = 1$
$\beta = B / D = Zsm - (1 - Yom\ Zsm)Zss$
$\Gamma = C / A = Yom$

Zsm : measured impedance of short chip
Zss : residual impedance of short chip (0.771nH)
Yom: measured admittance when opening the fixture

(4) Lx and Qx shall be calculated with the following equation.

$$Lx = \frac{Im(Zx)}{2\pi f}, \quad Qx = \frac{Im(Zx)}{Re(Zx)}$$

Lx : Inductance of chip coil
Qx : Q of chip coil
f : Measuring frequency